SimpleLink™ 6LoWPAN/ZigBee® CC2630 Wireless Microcontroller



Key features of the CC2630

- Industry's lowest power wireless
 MCII
 - Ultra-low power sensor controller and lowest RF peak current enabling multi-year operation on a coin cell battery
 - Sensor controller and peripherals can be powered while rest of system is powered off

High performance

- Abundant processing power with an ARM® Cortex®-M3 application processor clocked up to 48 MHz and supported by a dedicated radio co-processor. In standby mode, the sensor controller engine (SCE) monitors, logs and acts on sensor inputs at 1 μA current consumption, providing an ideal solution for any low-power nodes in ZigBee, 6LoWPAN and IEEE 802.15.4 mesh networks
- High link budget (up to 105dB) for a larger communication area and more nodes in the network
- Multiple protocol support with ZigBee, 6LoWPAN and 802.15.4 mesh

Smallest solution size

- Save space with 4×4 mm QFN package
- Additional sizes of 5×5 mm and 7×7 mm with up to 31 GPIOs
- All solutions include on-chip Flash memory, RAM and DC/DC converter

The SimpleLink™ 6LoWPAN/ZigBee® CC2630 wireless

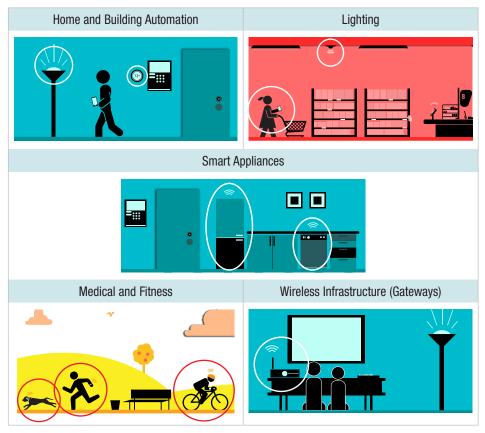


6LoWPAN, ZigBee and IEEE 802.15.4 standards.

Overview

The SimpleLink 6LoWPAN/ZigBee CC2630 wireless MCU enables ultra-low power operation on that can power a light switch for 10 years using a coin cell battery. The CC2630 can support the largest networks, connecting 1000s of nodes in homes, buildings and cities with a versatile portfolio of 802.15.4-based solutions. The CC2630 also has easy IP and cloud connectivity, using 6LoWPAN to give each device its own IPv6 address.

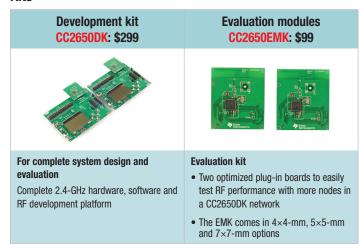
The CC2630 is designed for a broad range of applications including:



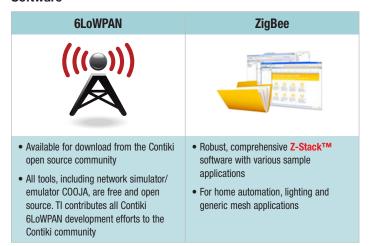
Getting started:

Evaluate the CC2630 on the CC2650-based development kits

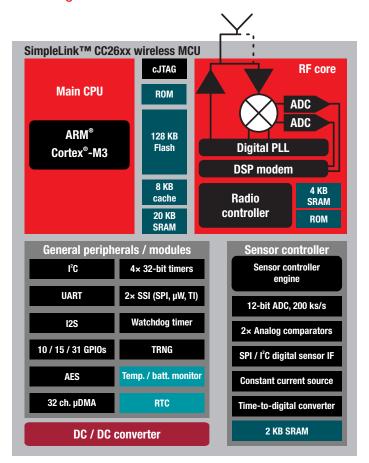
Kits



Software



Block diagram:



For more information on the SimpleLink ultra-low power wireless MCU platform, please visit **www.ti.com/simplelinkulp**

The platform bar, SimpleLink and Z-Stack are trademarks of Texas Instruments. All other trademarks are the property of their respective owners.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products	Applications
Products	Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive **Amplifiers** amplifier.ti.com Communications and Telecom www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical Logic Security www.ti.com/security logic.ti.com

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity www.ti.com/wirelessconnectivity